

# INTERNATIONAL STANDARD

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**Semiconductor devices – Mechanical and climatic test methods –  
Part 5: Steady-state temperature humidity bias life test**





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IEC Central Office  
3, rue de Varembe  
CH-1211 Geneva 20  
Switzerland

Tel.: +41 22 919 02 11  
Fax: +41 22 919 03 00  
[info@iec.ch](mailto:info@iec.ch)  
[www.iec.ch](http://www.iec.ch)

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**Semiconductor devices – Mechanical and climatic test methods –  
Part 5: Steady-state temperature humidity bias life test**

INTERNATIONAL  
ELECTROTECHNICAL  
COMMISSION

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**SEMICONDUCTOR DEVICES –  
MECHANICAL AND CLIMATIC TEST METHODS –****Part 5: Steady-state temperature humidity bias life test**

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International Standard IEC 60749-5 has been prepared by IEC technical committee 47: Semiconductor devices.

This second edition cancels and replaces the first edition published in 2003. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) correction of an error in an equation;
- b) inclusion of notes for guidance;
- c) clarification of the applicability of test conditions.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
47/2367/FDIS	47/2383/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 60749 series, published under the general title *Semiconductor devices – Mechanical and climatic test methods*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

## SEMICONDUCTOR DEVICES – MECHANICAL AND CLIMATIC TEST METHODS –

### Part 5: Steady-state temperature humidity bias life test

#### 1 Scope

This part of IEC 60749 provides a steady-state temperature and humidity bias life test for the purpose of evaluating the reliability of non-hermetic packaged solid-state devices in humid environments.

This test method is considered destructive.

#### 2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60749-4, *Semiconductor devices – Mechanical and climatic test methods – Part 4: Damp heat, steady-state, highly accelerated stress test (HAST)*

#### 3 Terms and definitions

No terms and definitions are listed in this document.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at <http://www.electropedia.org/>
- ISO Online browsing platform: available at <http://www.iso.org/obp>

#### 4 General

This test employs conditions of temperature, humidity and bias which accelerate the penetration of moisture through the external protective material (encapsulant or seal) or along the interface between the external protective material and the metallic conductors which pass through it.

Where both this steady-state, humidity bias test and the damp heat, highly accelerated stress test (HAST) of IEC 60749-4 are performed, the results of this 85 °C/85 % RH steady-state test will take priority over the results of the HAST test, which is an accelerated test designed to activate the same failure mechanisms.